

**Part Number:101-00318-\*\***

**SIM + Micro SD P/P Card Conn.**

- Push-push eject type
- SMT
- Application for mobile phones

**1.Materials:**

Housing: High temperature thermoplastic,  
UL 94V-0 rated.  
Contact: Copper alloy  
Cover: SUS304 over nickel plating (50U" min)

**2.Contact finish:**

Selective 1~15u" gold plating on contact area,  
tin 160u" plating at solder tail, over nickel  
plating (50u"min)

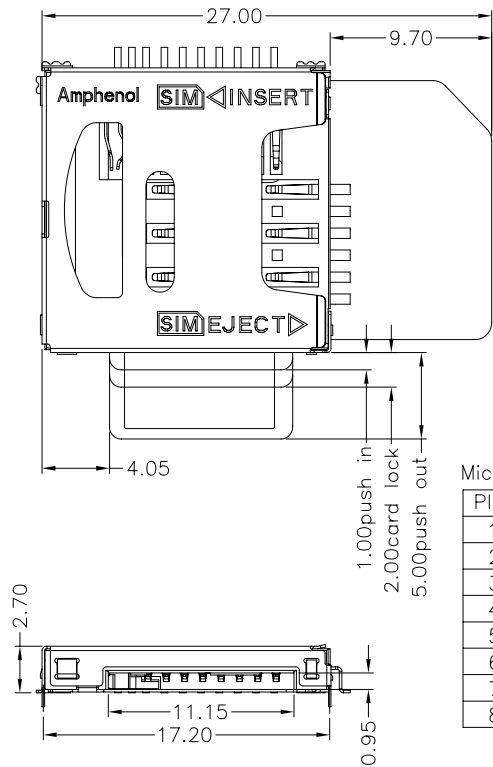
**3.Electrical specifications:**

Voltage Rating: 100VAC  
Current Rating: 0.5A per contact  
Dielectric strength: 500VAC initial and 250VAC  
final for one minute  
Insulation Resistance: 1000MΩ min at 500VDC  
Contact Resistance: 100mΩ max at 100mA  
Operating temperature: -25°C~+70°C

**4.Mechanical specifications:**

Durability: 5000cycles.  
Micro SD Card Mating force: 13.8N max.  
Micro SD Card Unmating force: 1N max  
Sim Card Mating force: 10N max.  
Sim Card Unmating force: 0.3N max

**5.RoHS Compliant**

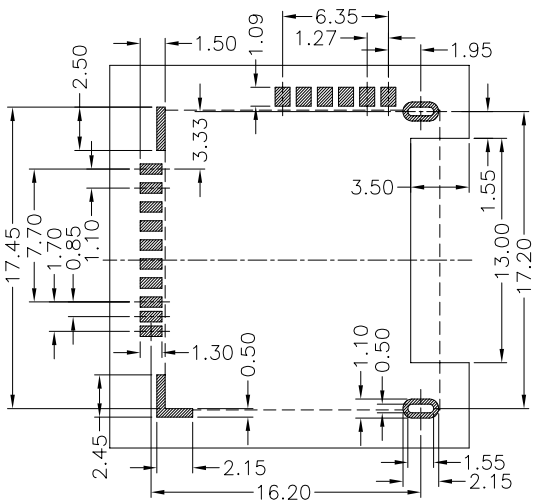


Micro-SD

PIN#	Name
1	DAT2
2	CD/DAT3 <sup>2</sup>
3	CMD
4	VDD
5	CLK
6	Vss
7	DAT0
8	DAT1

SIM CARD

PIN#	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved



PCB LAYOUT

